

A METHOD AND SYSTEM FOR A REJECT MANAGEMENT PROTOCOL WITHIN A BACK-END INTEGRATED CIRCUIT MANUFACTURING PROCESS

ABSTRACT OF THE DISCLOSURE

5 A method and system for a reject management protocol within a back-end IC manufacturing process. In one method embodiment, the present invention implements a tracking process for a die-strip. The present invention also maintains an electronic die-strip map database, and utilizes the tracking process to update the electronic die-strip map database as the die-strip moves in an in-line fashion from one sub-station to another within the manufacturing process. Information used to
10 update the database can originate from one or more automated visual camera systems used for quality assurance. In so doing, the present invention categorizes the die on the die-strip based on information maintained by the electronic die-strip map database. This information can be used for die sorting and for die rejection. In
15 one embodiment, an identifying code is placed on each die strip that can automatically identify the die-strip using the automated camera systems.